



# PMEG6020ETP

High-temperature 60 V, 2 A Schottky barrier rectifier

28 May 2018

Product data sheet

## 1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD128 small and flat lead Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Average forward current:  $I_{F(AV)} \leq 2$  A
- Reverse voltage:  $V_R \leq 60$  V
- Low forward voltage
- High power capability due to clip-bonding technology
- Small and flat lead SMD plastic package
- AEC-Q101 qualified
- High temperature  $T_j \leq 175$  °C
- Capable for reflow and wave soldering

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection

## 4. Quick reference data



Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_F$	forward current	$T_{sp} = 165$ °C	-	-	2.8	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20$ kHz; $T_{amb} \leq 120$ °C; square wave	[1]	-	2	A
		$\delta = 0.5$ ; $f = 20$ kHz; $T_{sp} \leq 170$ °C; square wave	-	-	2	A
$V_R$	reverse voltage	$T_j = 25$ °C	-	-	60	V
$V_F$	forward voltage	$I_F = 2$ A; $T_j = 25$ °C	-	460	530	mV
$I_R$	reverse current	$V_R = 60$ V; $t_p \leq 300$ $\mu$ s; $\delta \leq 0.02$ ; $T_j = 25$ °C; pulsed	-	60	150	$\mu$ A
$t_{rr}$	reverse recovery time	$I_F = 0.5$ A; $I_R = 0.5$ A; $I_{R(meas)} = 0.1$ A; $T_j = 25$ °C	-	8.6	-	ns

[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al<sub>2</sub>O<sub>3</sub>, standard footprint.

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 CFP5 (SOD128)	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG6020ETP	CFP5	plastic, surface mounted package; 2 terminals; 4 mm pitch; 3.8 mm x 2.6 mm x 1 mm body	SOD128

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG6020ETP	D9

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage	$T_j = 25\text{ °C}$		-	60	V
$I_F$	forward current	$T_{sp} = 165\text{ °C}$		-	2.8	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20\text{ kHz}$ ; $T_{amb} \leq 120\text{ °C}$ ; square wave	[1]	-	2	A
		$\delta = 0.5$ ; $f = 20\text{ kHz}$ ; $T_{sp} \leq 170\text{ °C}$ ; square wave		-	2	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8\text{ ms}$ ; square wave; $T_{j(init)} = 25\text{ °C}$		-	50	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[2]	-	750	mW
			[3]	-	1250	mW
			[1]	-	2500	mW
$T_j$	junction temperature			-	175	°C
$T_{amb}$	ambient temperature			-55	175	°C
$T_{stg}$	storage temperature			-65	175	°C

- [1] Device mounted on a ceramic Printed-Circuit Board (PCB),  $Al_2O_3$ , standard footprint.  
 [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.  
 [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode  $1\text{ cm}^2$ .

## 9. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	200	K/W
			[1] [3]	-	-	120	K/W
			[1] [4]	-	-	60	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	12	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.  
 [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.  
 [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode  $1\text{ cm}^2$ .  
 [4] Device mounted on a ceramic PCB,  $Al_2O_3$ , standard footprint.  
 [5] Soldering point of cathode tab.

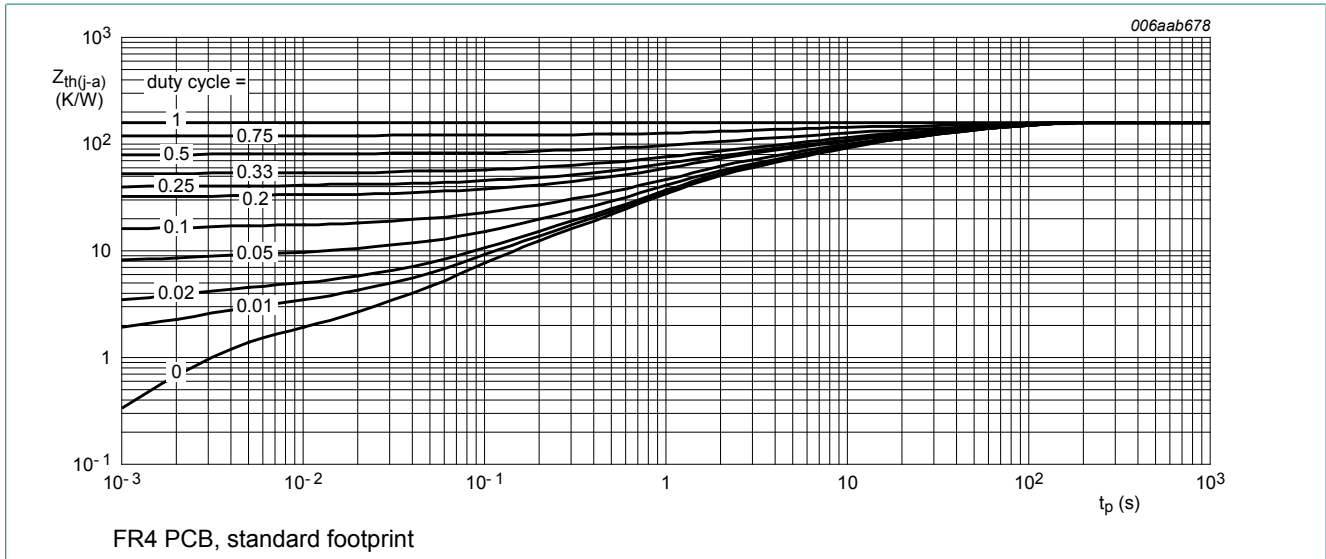


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

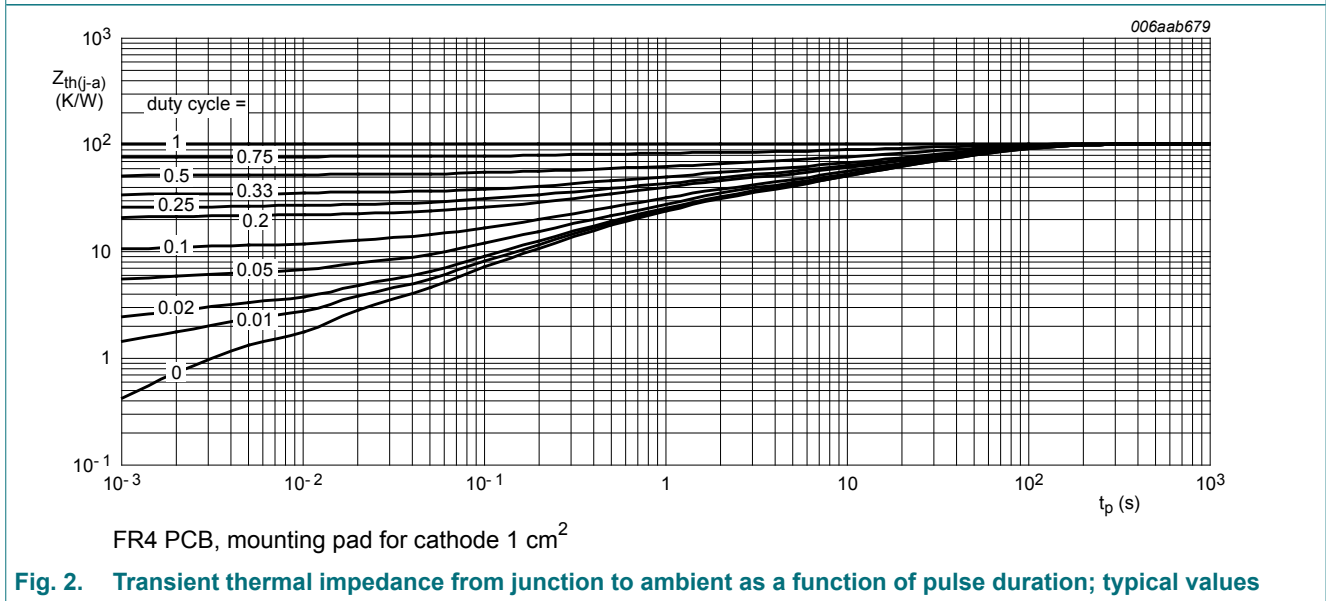
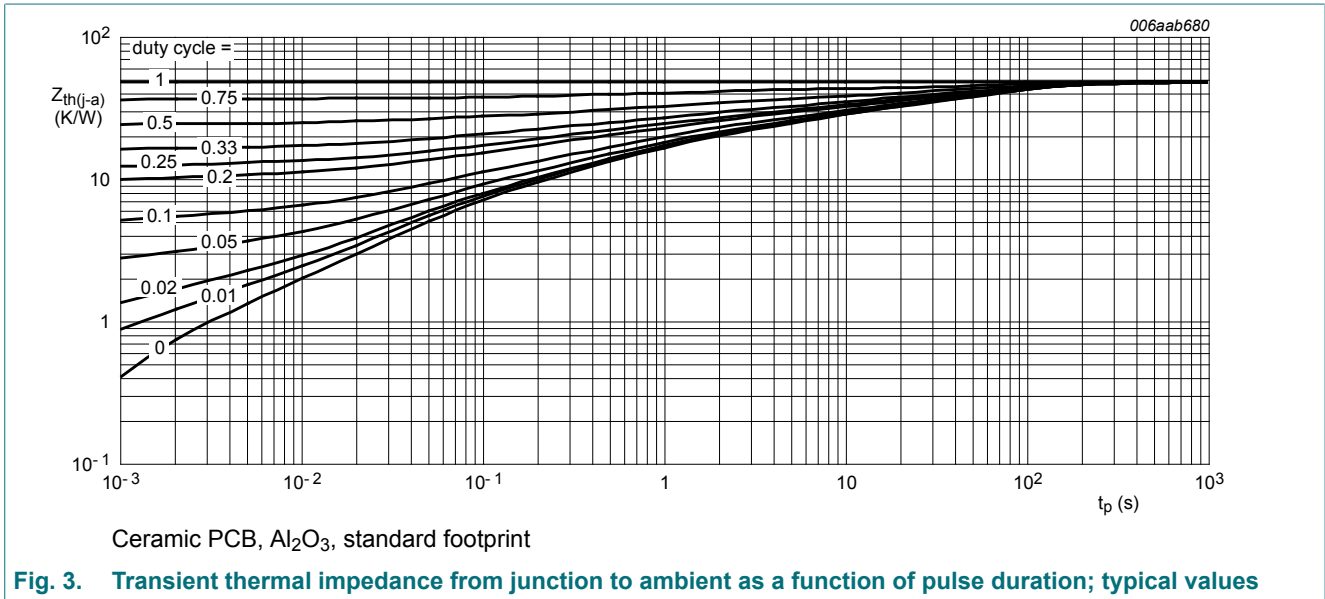


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 0.1 A; T <sub>j</sub> = 25 °C	-	300	340	mV
		I <sub>F</sub> = 0.5 A; T <sub>j</sub> = 25 °C	-	360	420	mV
		I <sub>F</sub> = 1 A; T <sub>j</sub> = 25 °C	-	400	460	mV
		I <sub>F</sub> = 1.5 A; T <sub>j</sub> = 25 °C	-	430	500	mV
		I <sub>F</sub> = 2 A; T <sub>j</sub> = 25 °C	-	460	530	mV
		I <sub>F</sub> = 2 A; T <sub>j</sub> = -40 °C	-	500	590	mV
		I <sub>F</sub> = 2 A; T <sub>j</sub> = 125 °C	-	395	480	mV
		I <sub>F</sub> = 2 A; T <sub>j</sub> = 150 °C	-	380	460	mV
		I <sub>F</sub> = 2 A; T <sub>j</sub> = 175 °C	-	360	450	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 5 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>j</sub> = 25 °C; pulsed	-	2.5	-	μA
		V <sub>R</sub> = 10 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>j</sub> = 25 °C; pulsed	-	3.5	-	μA
		V <sub>R</sub> = 60 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>j</sub> = 25 °C; pulsed	-	60	150	μA
		V <sub>R</sub> = 60 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>j</sub> = -40 °C; pulsed	-	0.9	15	μA
		V <sub>R</sub> = 60 V; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>j</sub> = 125 °C; pulsed	-	27	100	mA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C	-	240	-	pF
		V <sub>R</sub> = 10 V; f = 1 MHz; T <sub>j</sub> = 25 °C	-	80	-	pF
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 0.5 A; I <sub>R</sub> = 0.5 A; I <sub>R(meas)</sub> = 0.1 A; T <sub>j</sub> = 25 °C	-	8.6	-	ns
V <sub>FRM</sub>	peak forward recovery voltage	I <sub>F</sub> = 1 A; dI <sub>F</sub> /dt = 40 A/μs; T <sub>j</sub> = 25 °C	-	401	-	mV

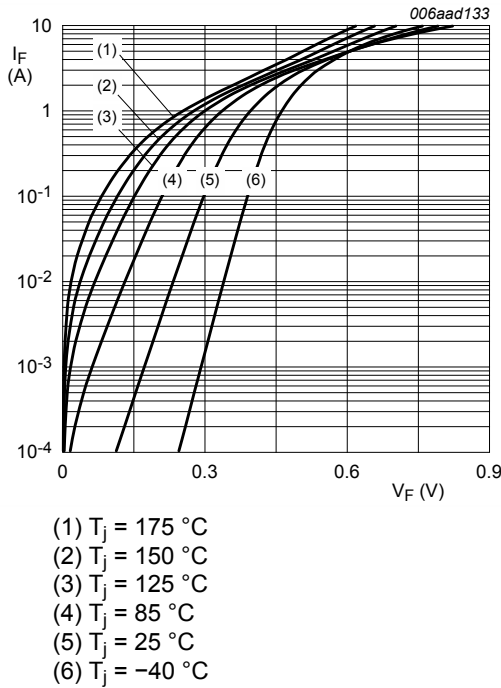


Fig. 4. Forward current as a function of forward voltage; typical values

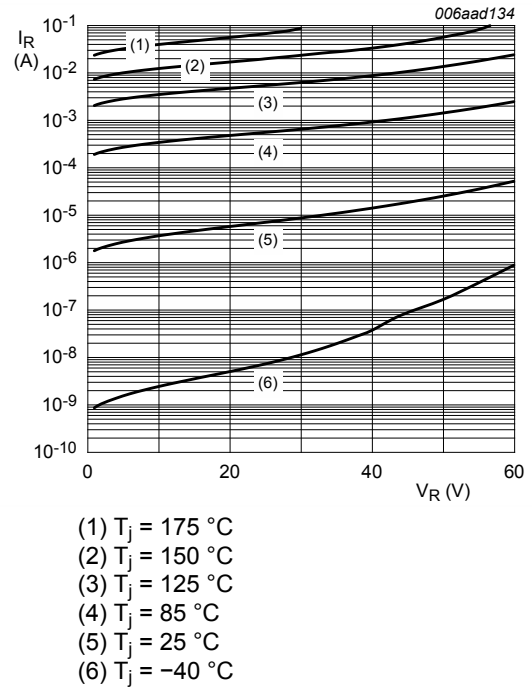


Fig. 5. Reverse current as a function of reverse voltage; typical values

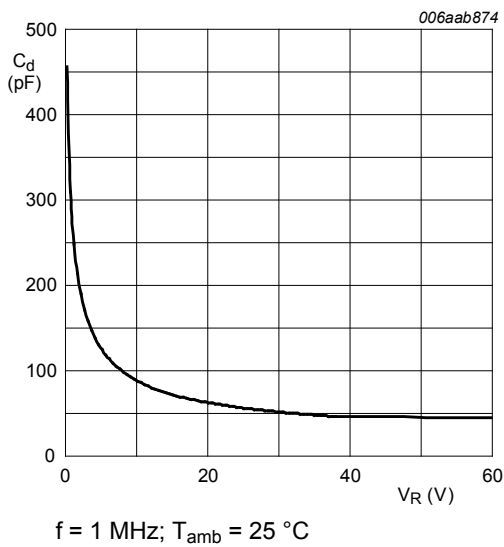


Fig. 6. Diode capacitance as a function of reverse voltage; typical values

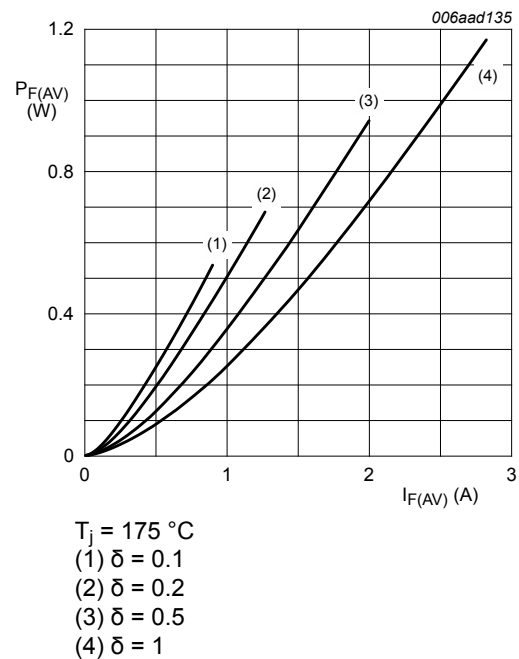


Fig. 7. Average forward power dissipation as a function of average forward current; typical values

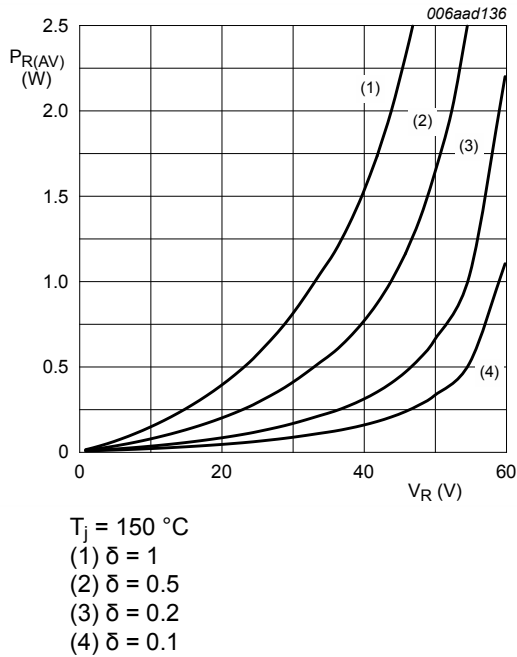


Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values

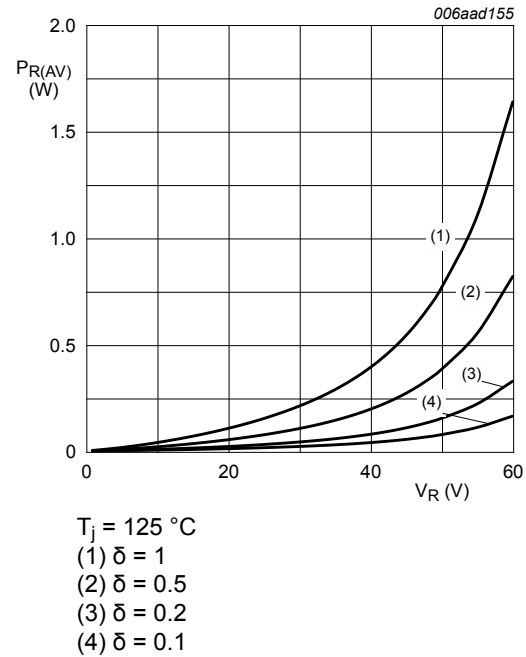


Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values

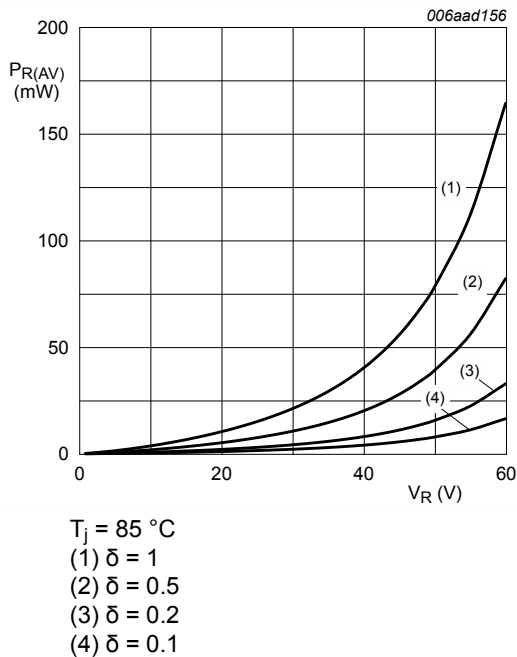


Fig. 10. Average reverse power dissipation as a function of reverse voltage; typical values

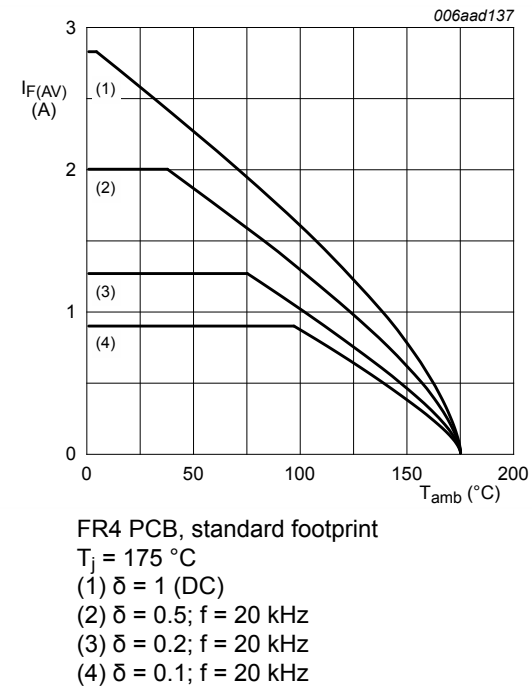
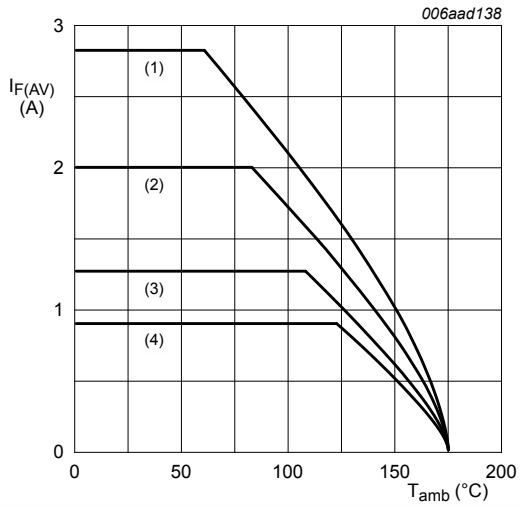


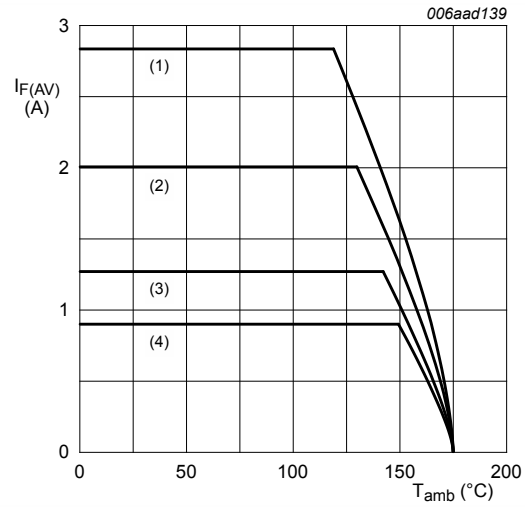
Fig. 11. Average forward current as a function of ambient temperature; typical values





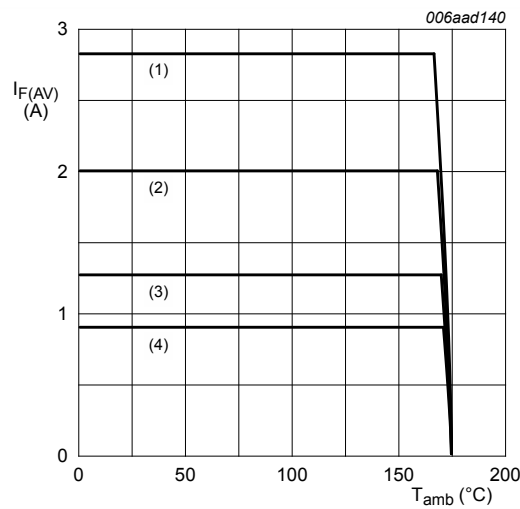
FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  
 $T_j = 175\text{ °C}$   
 (1)  $\delta = 1$  (DC)  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 12. Average forward current as a function of ambient temperature; typical values**



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint  
 $T_j = 175\text{ °C}$   
 (1)  $\delta = 1$  (DC)  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 13. Average forward current as a function of ambient temperature; typical values**



$T_j = 175\text{ °C}$   
 (1)  $\delta = 1$  (DC)  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 14. Average forward current as a function of solder point temperature; typical values**

### 11. Test information

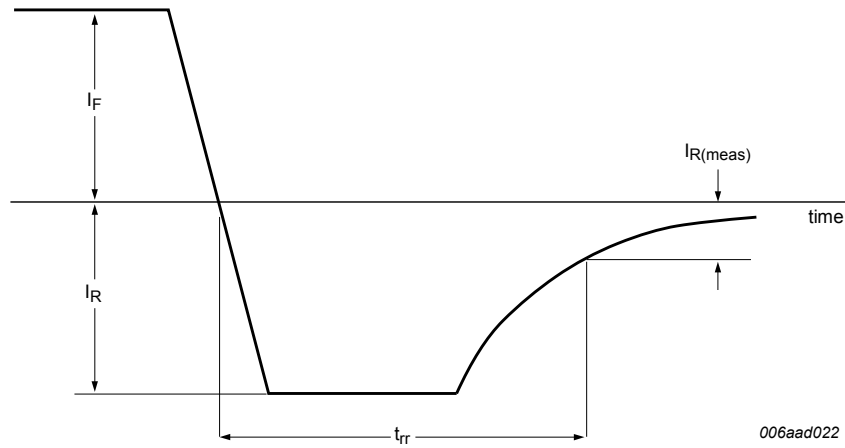


Fig. 15. Reverse recovery definition

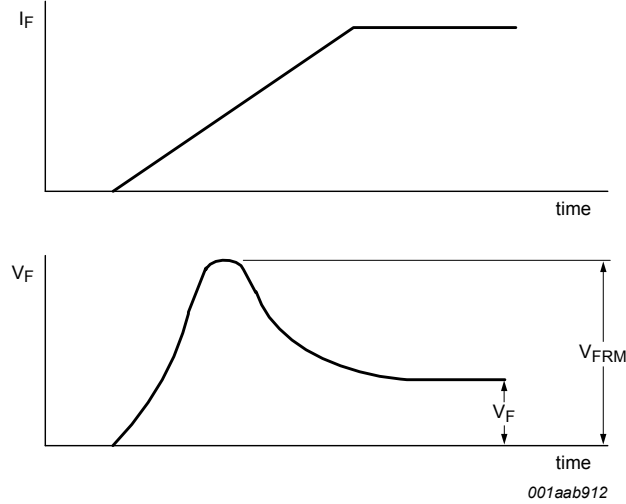


Fig. 16. Forward recovery definition

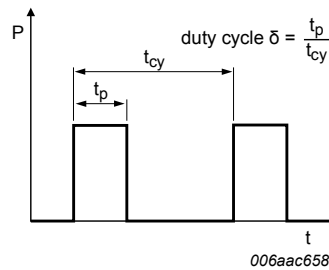


Fig. 17. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:  
 $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,  $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.

**Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

**12. Package outline**

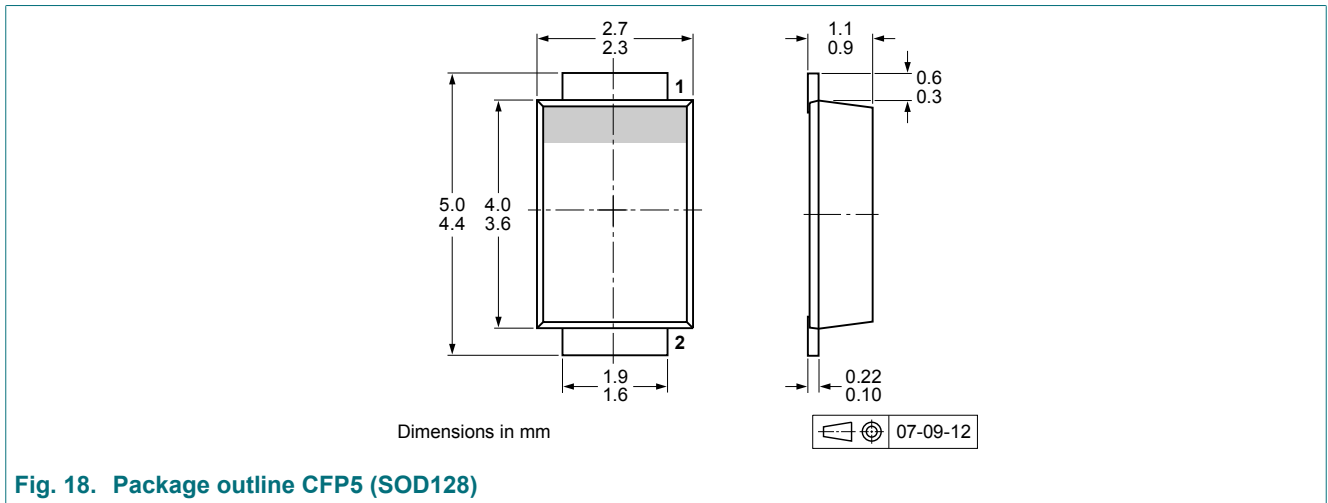


Fig. 18. Package outline CFP5 (SOD128)

**13. Soldering**

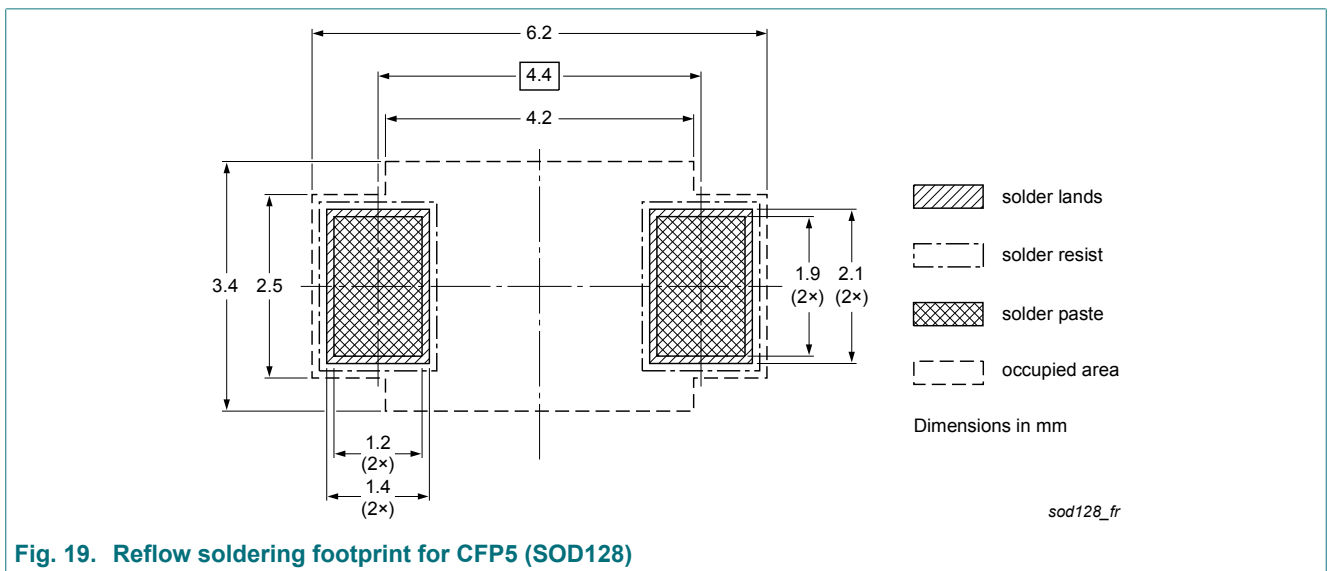
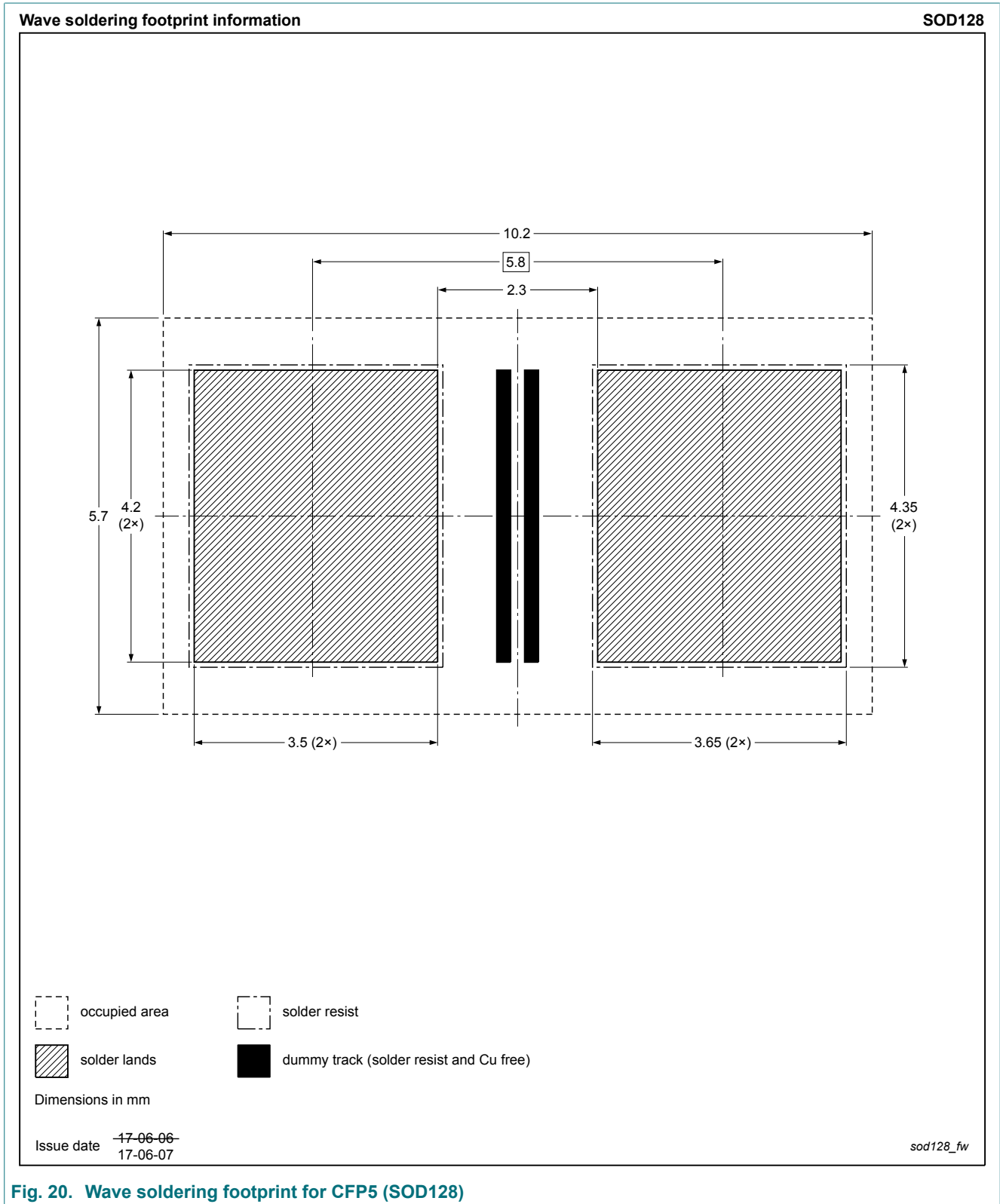


Fig. 19. Reflow soldering footprint for CFP5 (SOD128)



**Fig. 20. Wave soldering footprint for CFP5 (SOD128)**

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG6020ETP v.2	20180528	Product data sheet	-	PMEG6010EP v.1
Modifications:	<ul style="list-style-type: none"><li>• Features and benefits: Capable for reflow and wave soldering added</li><li>• Soldering: Wave soldering footprint added</li></ul>			
PMEG6020ETP v.1	20121011	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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